

**ABSTRACT**

An apparatus and method for cable management via hook and loop type materials are provided. The apparatus includes a substrate and a tie wrap. In at least one embodiment, the substrate is coupled to a rigid frame that is capable of accommodating a plurality of cables. The substrate and the tie wrap each have engaging mechanisms that enable them to create a hook and loop type releasable bond when pressed into contact with each other. The tie wrap is shaped to define an elongated body and a head portion having an interior opening. The body of the tie wrap may be pulled through the interior opening of the head portion in order to provide support for cables.

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